

DUG'21 – 5<sup>th</sup> edition

# DAOS User Group

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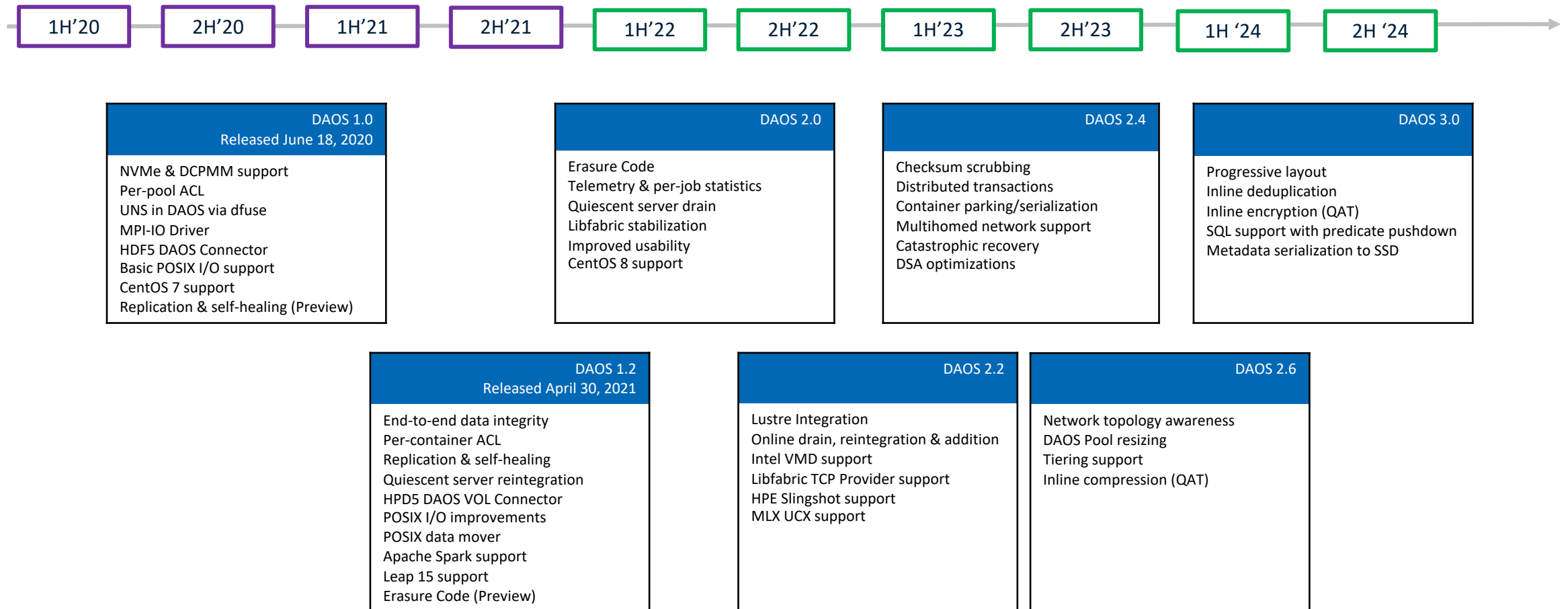
# Agenda

Time (CT)	Presentation
8:50am	<b>Welcome &amp; DAOS Update</b> Kelsey Prantis, DAOS team manager, Intel AXG
9:00am	<b>DAOS Async API Support &amp; Performance Tunning in Spark</b> Jiafu Zhang, Big Data Machine Learning Engineer, Intel SATG
9:20am	<b>DAOS Feature Update</b> Liang Zhen, DAOS architect, Intel AXG
9:40am	<b>Status and Roadmap of ROOT's RNTuple and DAOS</b> Javier Lopez Gomez, EP R&D Fellow, CERN
10:00am	<b>High Energy Physics experiment data processing with DAOS in multi-tier storage environment based on RSC Storage on-Demand</b> Martin Vala, Senior Researcher, JINR Pavel Lavrenko, Chief Business Development Officer, RSC Group Anton Brekhov, Team Lead, RSC Group
10:20am	<b>Break</b>
10:30am	<b>Leveraging DAOS storage system for seismic data storage</b> Omar Marzouk, Associate Software Engineer, Brightskies
10:50pm	<b>Lenovo Update</b> Sigrun Eggerling, DAOS POC Lead, Lenovo Steve Eiland, HPC Storage Product Management, Lenovo

Time (CT)	Presentation
11:10am	<b>Assessment of DAOS as a backend for ECMWF's FDB</b> Nicolau Manubens, Analyst, ECMWF
11:30am	<b>Moving DAOS from a Lab to a Commercial Offering</b> Darren Soothill, VP of Presales, Croit
11:50am	<b>Break</b>
12:00pm	<b>Tools to Migrate and Store DAOS containers on POSIX filesystems</b> Danielle Sikich, DAOS developer, Intel AXG
12:20pm	<b>DAOS Updates from HPE</b> Lance Evans, HPC CTO Chief Storage Architect, HPE
12:40pm	<b>Update on Omni-Path Express Support for DAOS</b> Paul Stasurak, Program Manager for Storage, Cornelis Networks
1:00pm	<b>DAOS on Google Cloud Platform</b> Carlos Boneti, HPC Software Engineer, Google Johann Lombardi, Lead DAOS architect, Intel AXG
1:20pm	<b>Closing remarks</b> Kelsey Prantis, DAOS team manager, Intel AXG

- Reminder: we have a very full agenda; agenda times will be strictly enforced
- All sessions today will be recorded and posted on our YouTube channel at <https://bit.ly/3pHHxcl>

# DAOS Roadmap



**NOTE: All information provided in this roadmap is subject to change without notice.**

# DAOS Ecosystem

<p>Hardware Partners</p>	
<p>Reseller Partners</p>	
<p>Software Development and 3<sup>rd</sup> party support</p>	
<p>End Customers</p>	

# DAOS L3 Technical Support

- Intel DAOS team to provide commercial L3 support to partners
- 3Y is the minimum support contract, with ability to extend
- Fulfillment:
  - MMID SKU standard delivery process
  - Sized based on the total hardware
- Escalation Path
  - PoC program – early engagement/PoCs will have access to our open-source community support Mailing list + Slack channel, without guaranteed SLAs
  - Community JIRA tickets for tracking L2 to L3 escalation

# Join Us!

- Hiring a Customer Support & Enablement Engineering Manager
- Responsibilities Include:
  - Coordinating a team in the diagnosis, design, and implementation of solutions to complex technical challenges
  - Understanding features from existing documentation and discussions with technical leaders
  - Fostering good development practices that result in maintainable, scalable, and on-time code
  - Maintaining documentation of team schedules, progress, and performance
  - Providing day-to-day guidance on prioritization of work amongst multiple deliverables
  - Managing customer and partner relationships, and coordinate engineering activities between Intel, partners, and end customer deployments
- Flexible Location
- <https://bit.ly/3DA5iK4>

# A few fun stats

- Since DAOS 1.2.0...
  - 1,427 commits
  - +375,092, -138,474 lines of code
  - Contributions from 51 developers in 9 different countries





# Resources

## Community Website & Documentation

- <https://daos.io>

## Source code on GitHub

- <https://github.com/daos-stack/daos>

## Community mailing list

- [daos@daos.groups.io](mailto:daos@daos.groups.io)

## Community Slack channel

- <https://bit.ly/38SOLEy>

## Support

- <https://jira.hpdd.intel.com>

## Intel DAOS Website

- <https://www.intel.com/content/www/us/en/high-performance-computing/daos.html>

## DAOS solution brief

- <https://www.intel.com/content/www/us/en/high-performance-computing/>

## DAOS technical paper from SCA'20

- <https://rdcu.be/caYtU>

## DAOS YouTube channel:

- <https://bit.ly/3pHHxcl>

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